SDAS048D - DECEMBER 1989 - REVISED JANUARY 1995

- 3-State Buffer-Type Outputs Drive Bus Lines Directly
- Bus-Structured Pinout
- True Logic Outputs
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), Standard Plastic (N) and Ceramic (J) 300-mil DIPs, and Ceramic Flat (W) Packages

description

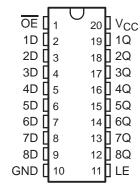
These octal D-type transparent latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

While the latch-enable (LE) input is high, outputs (Q) respond to the data (D) inputs. When LE is low, the outputs are latched to retain the data that was set up.

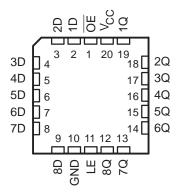
A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without interface or pullup components.

OE does not affect internal operation of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

SN54ALS573C, SN54AS573A . . . J OR W PACKAGE SN74ALS573C, SN74AS573A . . . DW OR N PACKAGE (TOP VIEW)



SN54ALS573C, SN54AS573A . . . FK PACKAGE (TOP VIEW)



The SN54ALS573C and SN54AS573A are characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ALS573C and SN74AS573A are characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each latch)

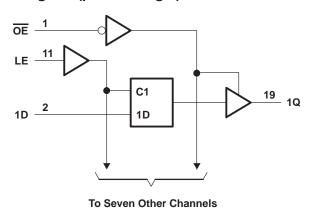
	INPUTS		OUTPUT
OE	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	Q_0
Н	Χ	Χ	Z

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logic symbol†

OE ΕN 11 LE C1 2 19 1D 1D **1Q** 18 3 2Q 2D 4 17 3D **3Q** 5 16 4D 4Q 6 15 5D 5Q 7 14 6D 6Q 8 13 7D 7Q 9 12 8D

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V _{CC}	7 V
Input voltage, V _I	7 V
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, T _A : SN54ALS573C	55°C to 125°C
SN74ALS573C	0°C to 70°C
Storage temperature range	65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SNS	4ALS57	3C	SN7	4ALS57	3C	LIAUT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.7			0.8	V
ІОН	High-level output current			-1			-2.6	mA
lOL	Low-level output current			12			24	mA
t _W	Pulse duration, LE high	25			10			ns
t _{su}	Setup time, data before LE↓	10			10			ns
th	Hold time, data after LE↓	7			7			ns
TA	Operating free-air temperature	-55		125	0		70	°C

[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

242445752		TEST CONDITIONS				SN7	4ALS57	3C	LINUT	
PARAMETER	TEST C	ONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
VIK	$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V	
	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	2		VCC -2	2			
∨он	V 45V	I _{OH} = -1 mA	2.4	3.3					V	
	V _{CC} = 4.5 V	$I_{OH} = -2.6 \text{ mA}$				2.4	3.2			
.,	V 45V	I _{OL} = 12 mA		0.25	0.4		0.25	0.4	.,	
V _{OL}	V _{CC} = 4.5 V	I _{OL} = 24 mA					0.35	0.5	V	
lozh	V _{CC} = 5.5 V,	V _O = 2.7 V			20			20	μΑ	
lozL	V _{CC} = 5.5 V,	V _O = 0.4 V			-20			-20	μΑ	
lį	V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA	
lін	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ	
I _{IL}	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.13			-0.1	mA	
I _O ‡	V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA	
		Outputs high		10	17		10	17	mA	
ICC	V _C C = 5.5 V	Outputs low		15	24		15	24		
		Outputs disabled		16	27		16	27		

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C _l R1 R2	V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R1 = 500 Ω , R2 = 500 Ω , T _A = MIN to MAX§						
			SN54AL	S573C	SN74AL	S573C				
			MIN	MAX	MIN	MAX				
^t PLH	6	0	2	20	2	14				
t _{PHL}	D	Q	2	17	2	14	ns			
t _{PLH}		_	8	33	6	20				
t _{PHL}	LE	Q	8	24	6	19	ns			
^t PZH	ŌĒ	_	4	28	3	18				
^t PZL	OE	Q	4	21	4	18	ns			
^t PHZ	ŌĒ	Q	2	20	1	10	ne			
t _{PLZ}	OE	Q	3	26	1	15	ns			

[§] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. ‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}		7 V
Input voltage, V _I		7 V
Voltage applied to a disabled 3-state outp	ut	5.5 V
Operating free-air temperature range, T _A :	SN54AS573A	–55°C to 125°C
	SN74AS573A	0°C to 70°C
Storage temperature range		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN	54AS573	3A	SN	74AS573	LINUT	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			8.0			0.8	V
IOH	High-level output current			-12			-15	mA
lOL	Low-level output current			32			48	mA
t _W *	Pulse duration, LE high	5.5			4.5			ns
t _{su} *	Setup time, data before LE↓	2			2			ns
th*	Hold time, data after LE↓	3		·	3			ns
TA	Operating free-air temperature	-55		125	0		70	°C

^{*} On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CONDITIONS				SN	74AS57	3A	LINUT	
PARAMETER	TEST C	ONDITIONS	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT	
VIK	$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V	
	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V _{CC} -2	2		V _{CC} -2	2			
Vон	V 45V	I _{OH} = -12 mA	2.4	3.2					V	
	V _{CC} = 4.5 V	$I_{OH} = -15 \text{ mA}$				2.4	3.3			
.,	V 45V	I _{OL} = 32 mA		0.28	0.5				V	
VOL	V _{CC} = 4.5 V	I _{OL} = 48 mA					0.33	0.5	V	
lozh	V _{CC} = 5.5 V,	V _O = 2.7 V			50			50	μΑ	
lozL	V _{CC} = 5.5 V,	V _O = 0.4 V			-50			-50	μΑ	
lį	V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA	
lН	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ	
I _{IL}	$V_{CC} = 5.5 V,$	V _I = 0.4 V			-0.1			-0.5	mA	
I _O §	$V_{CC} = 5.5 V$,	V _O = 2.25 V	-30		-112	-30		-112	mA	
		Outputs high		56	93		56	93		
ICC	V _C C = 5.5 V	Outputs low		55	90		55	90	mA	
		Outputs disabled		65	106		65	106		

 $[\]pm$ All typical values are at V_{CC} = 5 V, T_A = 25°C.

[§] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.



SN54ALS573C, SN54AS573A, SN74ALS573C, SN74AS573A OCTAL D-TYPE TRANSPARENT LATCHES WITH 3-STATE OUTPUTS SDAS048D - DECEMBER 1989 - REVISED JANUARY 1995

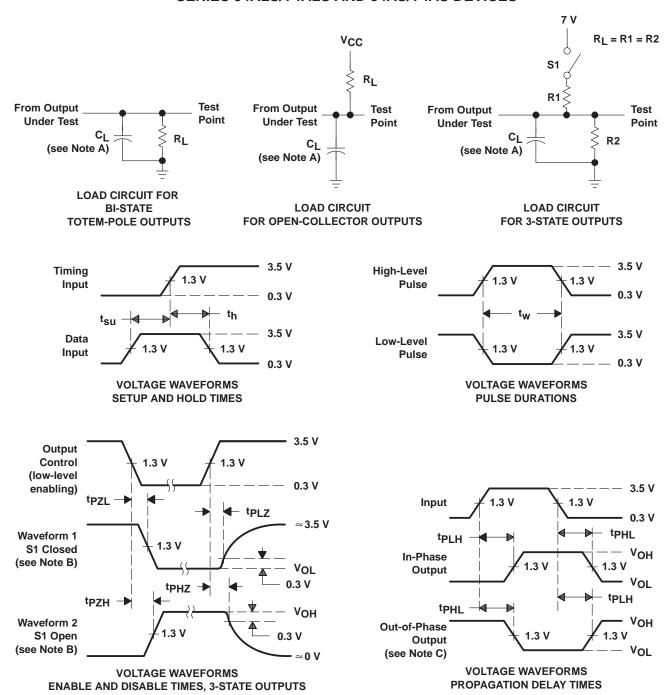
switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₍ C _I R1 R2 T ₂	UNIT				
			SN54AS	S573A	SN74AS	5573A		
			MIN	MAX	MIN	MAX		
tPLH	6	_	3	11	3	8	ns	
^t PHL	D	Q	3	8	3	7		
tPLH		_	6	16.5	6	13		
^t PHL	LE	Q	4	9	4	7.5	ns	
^t PZH	ŌĒ	_	2	8	2	6.5		
t _{PZL}	OE .	Q	4	11	4	9.5	ns	
^t PHZ	ŌĒ	Q	2	8	2	6.5		
^t PLZ	OE .	Q	2	8	2	7	ns	

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

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PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
84012012A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	84012012A SNJ54ALS 573CFK	Samples
8401201RA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8401201RA SNJ54ALS573CJ	Samples
8401201SA	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8401201SA SNJ54ALS573CW	Samples
JM38510/38201B2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 38201B2A	Samples
JM38510/38201BRA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 38201BRA	Samples
M38510/38201B2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 38201B2A	Samples
M38510/38201BRA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 38201BRA	Samples
SN54ALS573CJ	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54ALS573CJ	Samples
SN54AS573AJ	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54AS573AJ	Samples
SN74ALS573CDBR	ACTIVE	SSOP	DB	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	G573C	Samples
SN74ALS573CDW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70	ALS573C	
SN74ALS573CDWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS573C	Samples
SN74ALS573CN	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS573CN	Samples
SN74ALS573CNE4	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS573CN	Samples
SN74ALS573CNSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS573C	Samples
SN74ALS573CNSRE4	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS573C	Samples
SN74AS573ADW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	AS573A	Samples



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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AS573AN	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74AS573AN	Samples
SNJ54ALS573CFK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	84012012A SNJ54ALS 573CFK	Samples
SNJ54ALS573CJ	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8401201RA SNJ54ALS573CJ	Samples
SNJ54ALS573CW	ACTIVE	CFP	W	20	25	Non-RoHS & Non-Green	SNPB	N / A for Pkg Type	-55 to 125	8401201SA SNJ54ALS573CW	Samples
SNJ54AS573AJ	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54AS573AJ	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

PACKAGE OPTION ADDENDUM

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OTHER QUALIFIED VERSIONS OF SN54ALS573C, SN54AS573A, SN74ALS573C, SN74AS573A:

Catalog: SN74ALS573C, SN74AS573A

Military: SN54ALS573C, SN54AS573A

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS573CDBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ALS573CDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ALS573CNSR	so	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1



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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS573CDBR	SSOP	DB	20	2000	356.0	356.0	35.0
SN74ALS573CDWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS573CNSR	SO	NS	20	2000	367.0	367.0	45.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
84012012A	FK	LCCC	20	55	506.98	12.06	2030	NA
8401201SA	W	CFP	20	25	506.98	26.16	6220	NA
JM38510/38201B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
M38510/38201B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
SN74ALS573CN	N	PDIP	20	20	506	13.97	11230	4.32
SN74ALS573CNE4	N	PDIP	20	20	506	13.97	11230	4.32
SN74AS573ADW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74AS573AN	N	PDIP	20	20	506	13.97	11230	4.32
SNJ54ALS573CFK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54ALS573CW	W	CFP	20	25	506.98	26.16	6220	NA



SMALL OUTLINE PACKAGE



- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-150.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



INSTRUMENTS www.ti.com

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.

 D. Index point is provided on cap for terminal identification only.

 E. Falls within Mil—Std 1835 GDFP2—F20



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